



## Material Content Data Sheet



<b>Sales Product Name</b>		BCR 521 E6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000245956						
<b>Package</b>		PG-SOT23-3-4		<b>Weight*</b>		9.08 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		15	
	noble metal	gold	7440-57-5	0.013	0.14		1439	
	inorganic material	silicon	7440-21-3	0.112	1.23	1.37	12291	13745
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		996	
	inorganic material	silicon	7440-21-3	0.001	0.01		66	
	non noble metal	titanium	7440-32-6	0.003	0.03		332	
	non noble metal	copper	7440-50-8	3.001	33.06	33.20	330602	331996
wire	noble metal	gold	7440-57-5	0.014	0.16	0.16	1578	1578
encapsulation	organic material	carbon black	1333-86-4	0.091	1.00		10009	
	inorganic material	antimonytrioxide	1309-64-4	0.136	1.50		15014	
	plastics	brominated resin	-	0.170	1.88		18767	
	plastics	epoxy resin	-	1.420	15.64		156391	
	inorganic material	silicondioxide	60676-86-0	3.861	42.54	62.56	425385	625566
leadfinish	non noble metal	tin	7440-31-5	0.136	1.50	1.50	15029	15029
plating	noble metal	silver	7440-22-4	0.110	1.21	1.21	12086	12086
*deviation	< 10%		Sum in total:			100,00		1000000

### Important Remarks:

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